# 0.5 kHz to 125 MHz, MHz-to-kHz Programmable Clock

### **Features**

- · Designed for Very Low Power Applications
- · Accepts Crystal or Reference Clock Inputs
- · Input Frequency:
  - Fundamental Crystal: 10 MHz to 50 MHz
  - Reference Input: 1 MHz to 125 MHz
- · Accepts >0.1V Reference Signal Input Voltage
- Output Frequency 0.5 kHz to 125 MHz CMOS
  - 65 MHz at 1.8V Operation
  - 90 MHz at 2.5V Operation
  - 125 MHz at 3.3V Operation
- One Programmable I/O Pin Can be Configured as OE, PDB, FSEL, or CLK1
- · Low Current Consumption
  - <1.0 mA with 27 MHz and 32 kHz Outputs
  - <5 µA when PDB is Activated
- Single 1.8V ~ 3.3V, ±10% Power Supply
- · Operating Temperature Range:
  - -40°C to +85°C (Industrial)
  - 0°C to +70°C (Commercial)
- Available in 6-pin TDFN or SOT-23 GREEN/RoHS-Compliant Packaging

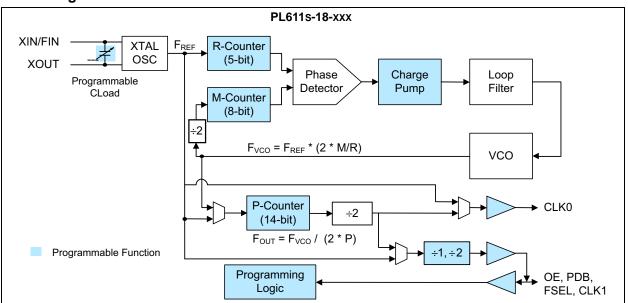
### **General Description**

The PL611s-18-xxx is a general purpose frequency synthesizer and a member of the PicoPLL family, the world's smallest programmable clocks. PL611s-18-xxx offers the versatility of using a single crystal (MHz) or reference clock input and producing up to two (kHz/MHz) system clocks, or a combination of reference and frequency low outputs. PL611s-18-xxx is designed for low-power applications with very stringent space requirements and consumes, for example, ~1.0 mA while producing two distinct outputs of 27 MHz and 32 kHz. The power down feature of the PL611s-18-xxx, when activated, allows the IC to consume less than 5 µA of power.

The PL611s-18-xxx fits in a small DFN-6L or SOT23-6L package. Cascading of the PL611s-18-xxx with other programmable clocks allows the generation of system level clocking requirements, thereby reducing the overall system implementation cost.

In addition, one programmable I/O pin can be configured as Output Enable (OE), Frequency switching (FSEL), Power Down (PDB) input, or CLK1 (CLK0, FREF, FREF/2) output.

### **Block Diagram**



### 1.0 ELECTRICAL CHARACTERISTICS

### **Absolute Maximum Ratings †**

Supply Voltage (V <sub>DD</sub> )	
Input Voltage (V <sub>IN</sub> )	0.5V to V <sub>DD</sub> + 0.5V
Output Voltage (V <sub>OUT</sub> )	–0.5V to V <sub>DD</sub> + 0.5V
ESD Rating (Note 1)	2 kV

### **Operating Ratings ‡**

**† Notice:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability. Parts are tested to commercial grade only.

**‡ Notice:** The device is not guaranteed to function outside its operating ratings.

Note 1: Devices are ESD sensitive. Handling precautions are recommended. Human body model, 1.5 k $\Omega$  in series with 100 pF.

TABLE 1-1: DC ELECTRICAL CHARACTERISTICS (Note 1)

**Electrical Characteristics:**  $V_{IN}$  = 3.3V;  $C_L$  = 15 pF;  $T_A$  = +25°C, **bold** values indicate -40°C  $\leq T_A \leq$  +85°C, unless noted.

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Supply Current, Power Down State	I <sub>DD</sub>	_	3.95	10.0	mA	$V_{\rm DD}$ = 3.3V, 27 MHz Xtal input, $F_{\rm VCO}$ = 81 MHz, CLK0 = 32.768 kHz, CLK1 = 27 MHz, Load = 15 pF
		_	2.35	3.5		$V_{DD}$ = 2.5V, 27 MHz Xtal input, $F_{VCO}$ = 81 MHz, CLK0 = 32.768 kHz, CLK1 = 27 MHz, Load = 10 pF
		l	1.30	2.0		$V_{\rm DD}$ = 1.8V, 27 MHz Xtal input, $F_{\rm VCO}$ = 81 MHz, CLK0 = 32.768 kHz, CLK1 = 27 MHz, Load = 5 pF
PLL Off Supply Current, Dynamic	I <sub>DD</sub>	l	2.75	9.0	mA	V <sub>DD</sub> = 3.3V, 27 MHz Xtal input, CLK0 = 32.768 kHz, CLK1 = 27 MHz, Load = 15 pF
			1.30	2.0		V <sub>DD</sub> = 2.5V, 27 MHz Xtal input, CLK0 = 32.768 kHz, CLK1 = 27 MHz, Load = 10 pF
		-	0.9	1.4		V <sub>DD</sub> = 1.8V, 27 MHz Xtal input, CLK0 = 32.768 kHz, CLK1 = 27 MHz, Load = 5 pF
Supply Current, Power Down State	I <sub>DD</sub>	_		5	μA	When PDB = 0
Operating Voltage	$V_{DD}$	1.62	_	3.63	V	_
Output Current, Low Drive	I <sub>OLD</sub>	4	_	_	mA	.,
Output Current, Standard Drive	I <sub>OSD</sub>	8	_	_	mA	$V_{OL} = 0.4V, V_{OH} = V_{DD} - 0.9V, V_{DD} = 3.3V$
Output Current, High Drive	$I_{OHD}$	16	_	_	mA	ייי טט ייי

Note 1: Specification for packaged product only.

### TABLE 1-2: AC ELECTRICAL CHARACTERISTICS (Note 1)

**Electrical Characteristics:**  $V_{IN}$  = 3.3V;  $C_L$  = 15 pF;  $T_A$  = +25°C, **bold** values indicate -40°C  $\leq T_A \leq$  +85°C, unless noted.

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Crystal Input Frequency	f <sub>IN(XTAL)</sub>	10	_	50	MHz	Fundamental Crystal
		1	_	125		V <sub>DD</sub> = 3.3V
Input Frequency	f <sub>IN</sub>	1	_	90	MHz	V <sub>DD</sub> = 2.5V
		1	_	65		V <sub>DD</sub> = 1.8V
		0.8	_	V <sub>DD</sub>		Internally AC-Coupled (high frequency)
Input (f <sub>IN</sub> ) Signal Amplitude	ignal Amplitude — 0.1 — V <sub>DD</sub>		V <sub>PP</sub>	Internally AC-Coupled (low frequency) 3.3V ≤50 MHz, 2.5V ≤40 MHz, 1.8V ≤15 MHz		
Output Frequency	f <sub>ОUТ</sub>	_	_	125		V <sub>DD</sub> = 3.3V
		_	_	90	MHz	V <sub>DD</sub> = 2.5V
		_	_	65		V <sub>DD</sub> = 1.8V

TABLE 1-2: AC ELECTRICAL CHARACTERISTICS (Note 1) (CONTINUED)

**Electrical Characteristics:**  $V_{IN}$  = 3.3V;  $C_L$  = 15 pF;  $T_A$  = +25°C, **bold** values indicate -40°C  $\leq T_A \leq$  +85°C, unless noted.

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Settling Time	_	_	_	2	ms	At power-up (after V <sub>DD</sub> increases over 1.62V)
Output Enable Time	t <sub>OE</sub>	_	_	100	μs	OE function; T <sub>A</sub> = +25°C, 15 pF load. Add one clock period for a usable output.
	OL.	_	_	2	ms	PDB function; T <sub>A</sub> = +25°C, 15 pF load.
V <sub>DD</sub> Sensitivity	_	-2	_	2	ppm	Frequency vs. V <sub>DD</sub> ±10%
Output Rise Time	t <sub>r</sub>	_	2	3	ns	15 pF load, 10/90% V <sub>DD</sub> , Standard Drive, 3.3V
Output Fall Time	t <sub>f</sub>	_	2	3	ns	15 pF load, 90/10% V <sub>DD</sub> , Standard Drive, 3.3V
Duty Cycle	_	45	50	55	%	V <sub>DD</sub> /2
Period Jitter, Peak-to-Peak (Note 2)	_	_	70	_	ps	With capacitive decoupling between V <sub>DD</sub> and GND. 10,000 samples measured.

Note 1: Specification for packaged product only.

TABLE 1-3: CRYSTAL SPECIFICATIONS

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions	
Fundamental Crystal Resonator Frequency	F <sub>XIN</sub>	10	_	50	MHz	_	
Crystal Loading Rating (The IC can be programmed for any value in this range.)	C <sub>L(XTAL)</sub>	8	_	12	pF	_	
Maximum Sustainable Drive Level	_	_	_	100	μW	_	
Operating Drive Level	_	_	30	_	μW	_	
Metal Can Crystal Shunt Capacitance	C0	_	_	5.5	pF	_	
Metal Can Crystal ESR max.	ESR	_	_	50	Ω	_	
Small SMD Crystal Shunt Capacitance	C0	_	_	2.5	pF	_	
Small SMD Crystal ESR max.	ESR	_	_	80	Ω	_	

**<sup>2:</sup>** Jitter performance depends on the programming parameters.

# **TEMPERATURE SPECIFICATIONS (Note 1)**

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions	
Temperature Ranges							
Storage Temperature Range	T <sub>S</sub>	-65	_	+150	°C	_	
Ambient Operating Temperature	T <sub>A</sub>	-40	_	+85	°C	Industrial	
Ambient Operating Temperature	T <sub>A</sub>	0	_	+70	°C	Commercial	
Junction Operating Temperature	TJ	_	_	+110	°C	_	
Lead Temperature	_	_	_	+260	°C	Soldering, 10 sec.	
Thermal Resistance							
Junction Thermal Resistance, 6-Ld TDFN	$\theta_{JA}$	_	100	_	°C/W	_	
Junction Thermal Resistance, 6-Ld SOT-23	$\theta_{JA}$	_	192	_	°C/W	_	

**Note 1:** Exposure of the device under conditions beyond the limits specified by the maximum ratings for extended periods may cause permanent damage to the device and affect product reliability. These conditions represent a stress rating only, and functional operations of the device at these or any other conditions above the operational limits noted in this specification is not implied. Operating temperature is guaranteed by design. Parts are tested to commercial grade only.

### 2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

## **Pin Configurations**

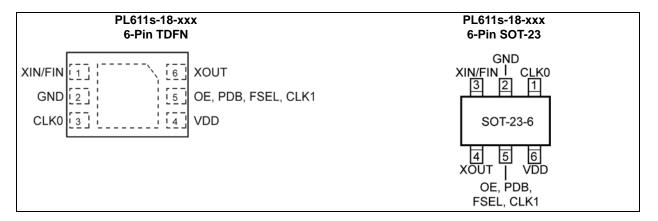


TABLE 2-1: PIN FUNCTION TABLE

6-Pin TDFN Pin Number	6-Pin SOT-23 Pin Number	Name	Туре	Description				
1	3	XIN, FIN	I	Crystal or refere	Crystal or reference input pin.			
2	2	GND	Р	GND connectio	n.			
3	1	CLK0	0	Programmable	clock output.			
4	6	VDD	Р	VDD connection	VDD connection.			
5	5	OE, PDB, FSEL, CLK1	I/O	This programmable I/O pin can be configured as an output enable (OE) input, power down (PDB) input, frequency select (FSEL) input, or CLK1 output. This pin has an internal 60 k $\Omega$ pull-up resistor on OE, PDB, and FSEL.				
				State	OE	PDB	FSEL	
				0	Tri-State CLK	Power Down Mode	Bank 0	
				1 (default)	Operating Mode	Operating Mode	Bank 1	
6	4	XOUT	0	Crystal output pin. Do not connect if FIN is used.				

### 3.0 FUNCTIONAL DESCRIPTION

PL611s-18-xxx is a highly featured, very flexible, advanced programmable PLL design for high performance, low-power, small form-factor applications. The PL611s-18-xxx accepts a crystal input of 10 MHz to 50 MHz or a reference clock input of 1 MHz to 125 MHz and is capable of producing two outputs up to 125 MHz. This flexible design allows the PL611s-18-xxx to deliver any PLL-generated frequency,  $F_{REF}$  (Crystal or Ref Clk) frequency or  $F_{REF}$   $\div$  (2 × P) to CLK0 and/or CLK1.

### 3.1 PLL Programming

The PLL in the PL611s-18-xxx is fully programmable. The PLL is equipped with a 5-bit input frequency divider (R-Counter) and an 8-bit VCO frequency feedback loop divider (M-Counter). The output of the PLL is transferred to a 14-bit post-VCO divider (P-Counter). The output frequency is determined by the following formula:

#### **EQUATION 3-1:**

$$F_{OUT} = F_{REF} \times M \div (R \times P)$$

### 3.2 Clock Output (CLK0)

CLK0 is the main clock output. The PL611s-18-xxx can also be programmed to provide a second clock output, CLK1, on the programmable I/O pin (see the OE/PDB/FSEL/CLK1 field of Table 2-1). The output of CLK0 can be configured as the PLL output ( $F_{VCO} \div (2 \times P)$ ),  $F_{REF}$  (Ref Clk Frequency) output, or  $F_{REF} \div (2 \times P)$  output. The output drive level can be programmed to Low Drive (4 mA), Standard Drive (8 mA), or High Drive (16 mA). The maximum output frequency is 125 MHz. Because of the long P counter, the minimum output frequency is as low as 0.5 kHz.

### 3.3 Clock Output (CLK1)

The CLK1 feature allows the PL611s-18-xxx to have an additional clock output. This output can be programmed to one of the following:

- F<sub>REF</sub>
- F<sub>REF</sub> ÷ 2
- CLK0
- CLK0 ÷ 2

### 3.4 Output Enable (OE)

The Output Enable feature allows the user to enable and disable the clock output and PLL by toggling the OE pin. Because the crystal remains operational when the output is disabled, the output enable time is much faster than with the Power Down function. The OE pin incorporates a 60 k $\Omega$  pull up resistor giving a default condition of logic "1". Pulling the OE pin low "0" will tri-state the output buffers.

### 3.5 Power Down Control (PDB)

The Power Down (PDB) feature allows the user to put the PL611s-18-xxx into sleep mode. When activated (logic '0'), PDB disables the PLL, the oscillator circuitry, counters, and all other active circuitry and tri-state the output buffers. In Power Down mode the IC consumes <5 µA of power. The PDB pin incorporates a pull-up resistor giving a default condition of logic "1".

### 3.6 Frequency Select (FSEL)

The Frequency Select (FSEL) feature allows the PL611s-18-xxx to switch between two pre-programmed outputs allowing the device on-the-fly frequency switching. The FSEL pin incorporates a 60 k $\Omega$  pull-up resistor giving a default condition of logic "1".

### 3.7 Programmable CLoad

The PL611s-18-xxx is equipped with programmable S-caps to allow the CLoad to be tuned from 8 pF to 12 pF.

### 4.0 LAYOUT RECOMMENDATIONS

The following guidelines are to assist you with a performance-optimized PCB design.

# 4.1 Signal Integrity and Termination Considerations

- · Keep traces short.
- Trace = Inductor. With a capacitive load this creates ringing.
- Long trace = Transmission Line. Without proper termination, this causes reflections that look like ringing.
- Design long traces (greater than one inch) as "striplines" or "microstrips" with defined impedance.
- Match the trace at one side to avoid reflections bouncing back and forth.

# 4.2 Decoupling and Power Supply Considerations

- Place decoupling capacitors as close as possible to the V<sub>DD</sub> pin(s) to limit noise from the power supply.
- Multiple V<sub>DD</sub> pins should be decoupled separately for best performance.

- The addition of a ferrite bead in series with V<sub>DD</sub> can help prevent noise from other board sources.
- The value of the decoupling capacitor is frequency-dependent. Typical values to use are 0.1 μF for designs using crystals <50 MHz and 0.01 μF for designs using crystals >50 MHz.

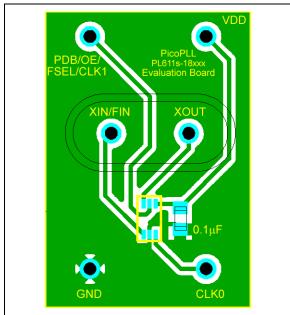


FIGURE 4-1: TDFN-6L Evaluation Board.

### 4.3 Typical CMOS Termination

Place series resistor as close as possible to the CMOS output.

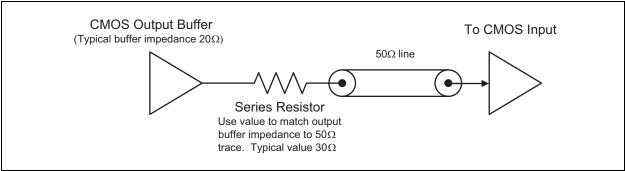
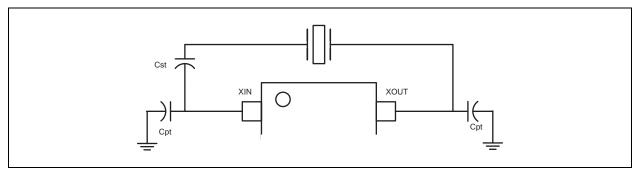


FIGURE 4-2: Typical CMOS Termination.

## 4.4 Crystal Tuning Circuit

Series and parallel capacitors are used to fine tune the crystal load to the circuit load.

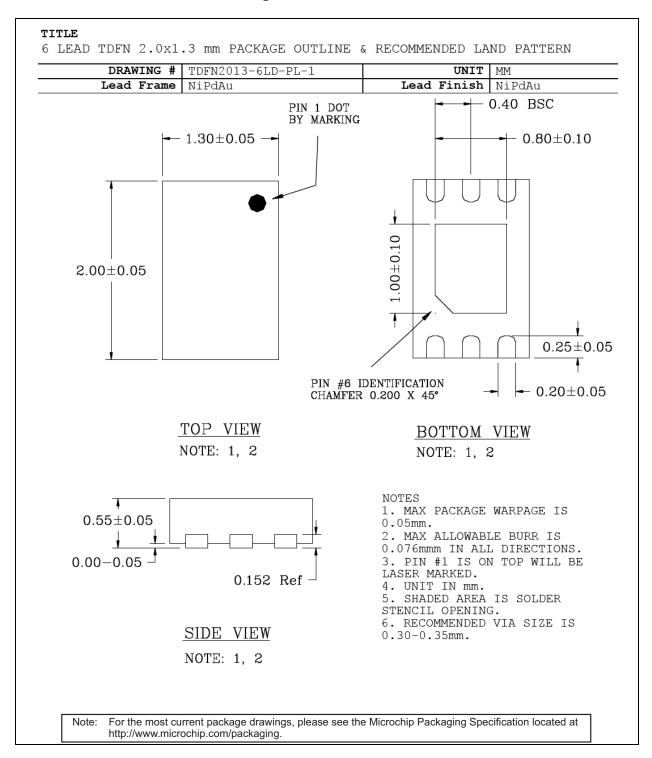


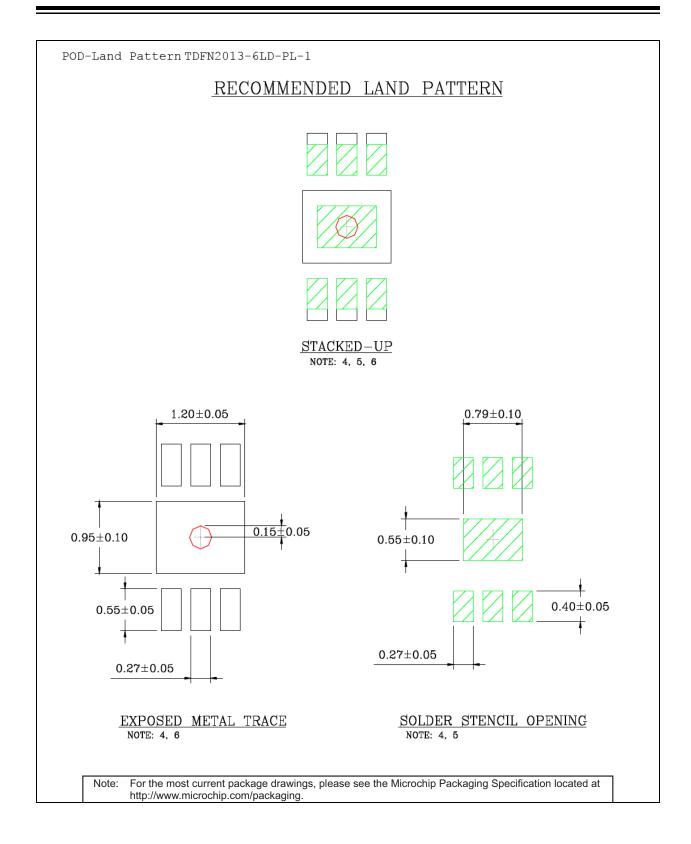
**CST:** Series capacitor, used to lower circuit load to match crystal load. Raises frequency offset. This can be eliminated by using a crystal with a CLoad of equal or greater value than the oscillator.

CPT: Parallel capacitors, used to raise the circuit load to match the crystal load. Lowers frequency offset.

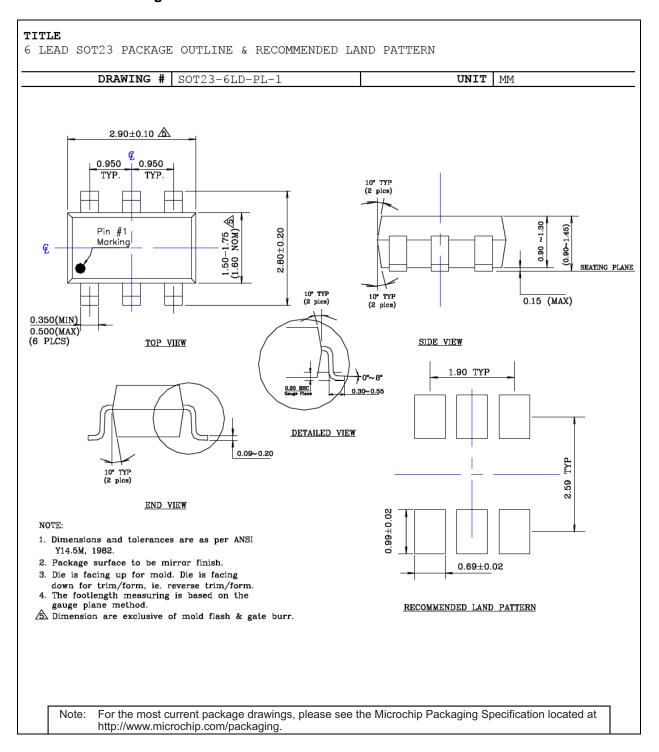
### 5.0 PACKAGING INFORMATION

### 6-Pin TDFN 2.0 mm x 1.3 mm Package Outline and Recommended Land Pattern





### 6-Pin SOT-23 Package Outline and Recommended Land Pattern



### APPENDIX A: REVISION HISTORY

### Revision A (March 2017)

- Converted Micrel document PL611s-18-xxx to Microchip data sheet DS20005741A.
- · Minor text changes throughout.
- Updated part numbering conventions in the Product Identification System to be consistent with Microchip system.
- Added Commercial temperature range throughout document.
- Correct package outline drawing added for 6-lead TDFN in Packaging Information.

**NOTES:** 

### PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO. — XXX X X X — X

Device ID Code Package Temperature Media Type

Device: PL611s-18:

0.5 kHz to 125 MHz, MHz-to-kHz Program-

mable Clock

ID Code: XXX =

3 Digit ID Code will be assigned at time of

programming

Package:

G = 6-Lead TDFN = 6-Lead SOT-23

Temperature:

C = 0°C to +70°C (Commercial)

-40°C to +85°C (Industrial)

Media Type:

Note

none = 20/Bag R = 3,000/Reel

Part Marking (Note 1)

TDFN Marking	SOT-23 Marking
XXX	18XXX
LLL	LLL

1: "XXX" designates a 3 digit number for the programmed, customized configuration. "LLL" designates a lot number.

**Examples:** 

a) PL611s-18-xxxGC: 0.5 kHz to 125 MHz, MHz-to-kHz

Programmable Clock, ID Code, 6-Lead TDFN, Commercial Temp.

Range, 20/Bag

b) PL611s-18-xxxGC-R: 0.5 kHz to 125 MHz,

MHz-to-kHz Programmable Clock, ID Code, 6-Lead TDFN,

Commercial Temp. Range,

3,000/Reel

c) PL611s-18-xxxGI:

0.5 kHz to 125 MHz, MHz-to-kHz Programmable Clock, ID Code, 6-Lead TDFN, Industrial Temp.

Range, 20/Bag

d) PL611s-18-xxxGI-R: 0.5 kHz to 125 MHz,

MHz-to-kHz Programmable Clock, ID Code, 6-Lead TDFN, Industrial Temp. Range,

3.000/Reel

e) PL611s-18-xxxTC: 0.5 kHz to 125 MHz, MHz-to-kHz

Programmable Clock, ID Code, 6-Lead SOT-23, Commercial Temp. Range, 20/Bag

f) PL611s-18-xxxTC-R: 0.5 kHz to 125 MHz,

MHz-to-kHz Programmable Clock, ID Code, 6-Lead SOT-23, Commercial Temp. Range,

3.000/Reel

g) PL611s-18-xxxTI: 0.5 kHz to 125 MHz, MHz-to-kHz

Programmable Clock, ID Code, 6-Lead SOT-23, Industrial Temp.

Range, 20/Bag

h) PL611s-18-xxxTI-R:  $0.5\,\mathrm{kHz}$  to  $125\,\mathrm{MHz}$ ,

MHz-to-kHz Programmable Clock, ID Code, 6-Lead SOT-23, Industrial Temp. Range,

3,000/Reel

Note 1:

Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

NOTES:

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